

ABSTRACT OF THE DISCLOSURE

A method of fabricating a surface-emission type light-emitting device which emits light in a direction perpendicular to a semiconductor substrate, includes the following steps (a) to (e). (a) A step of forming a column-shaped section by etching at least a part of a multilayer film. (b) A step of forming a first resin layer so as to cover the column-shaped section. (c) A step of forming a second resin layer by changing the solubility of the first resin layer in a liquid. (d) A step of immersing, for a specific period of time, at least the column-shaped section and the second resin layer in a liquid in which the second resin layer dissolves, thereby removing the second resin layer at least in the area formed over the column-shaped section. (e) A step of forming an insulating layer by curing the second resin layer.